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Dimensions	
Chip Size	1210
L	3.048mm +/-0.381mm (0.12 in +/-0.015 in)
W	2.54mm +/-0.381mm (0.1 in +/-0.015 in)
T	1.651mm MAX (0.065 in MAX)

Packaging Specifications	
Packaging	Waffle
Packaging Quantity	25000

General Information	
Series	SMD Mil PRF123
Style	SMD Chip
Description	SMD Chip, Temperature Stable
RoHS	No
Prop 65	⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov .
SCIP Number	8780fdfd-a0b3-4664-b80c-18c07cfab0d1
Termination	Tin
Failure Rate	N/A
AEC-Q200	No
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	0.027 uF
Capacitance Tolerance	10%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	BX
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vms
Dissipation Factor	2.5%
Insulation Resistance	100 GOhms

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